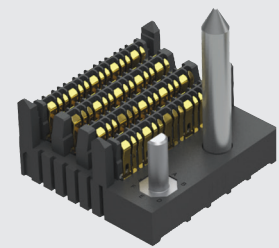


EBTM-6-12-2.0-S-VT-1



EBTM-4-08-2.0-S-VT-1-L-G

(2.00 mm) .0787"

ExaMAX[®] BACKPLANE SYSTEM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?EBTM or www.samtec.com?EBTF-RA

Insulator Material: Liquid Crystal Polymer

Contact Material: Copper Alloy

Plating: Sn or Au over

50 μm (1.27 μm) Ni

Operating Temp Range: -55 °C to +85 °C

Current Rating: 4.2 A per pin

(1 pin powered)

Contact Wipe: 2.4 mm

RoHS Compliant: Yes

EBTM Mates with:

EBTF-RA

EBTF-RA Mates with:

EBTM, EBDM

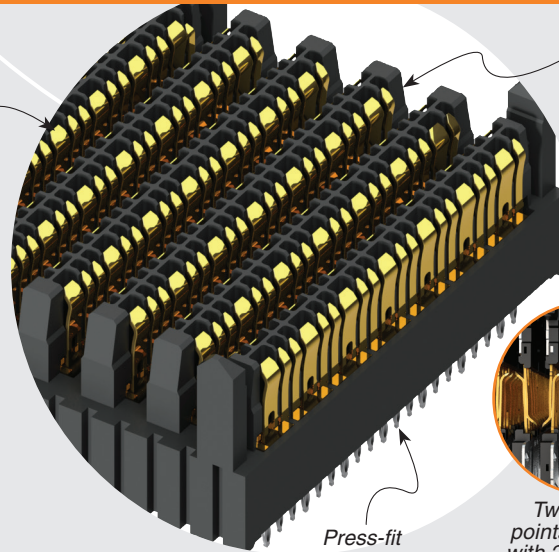
PAM 4

56
Gbps

2.00 mm
column pitch

Provides exceptionally low mating force while maintaining excellent normal force

APPLICATION



Press-fit termination

Two reliable points of contact with 2.4 mm wipe

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



TYPE

NO. OF PAIRS PER COLUMN

COLUMNS

COLUMN PITCH

ALSO AVAILABLE (MOQ Required)

- Staging
- Contact Samtec.

EBTM
= Vertical Header

EBTF
= Right-Angle Receptacle

-4
= 4 Pairs

-6
= 6 Pairs

-06

-08

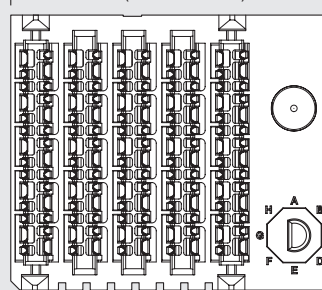
-10

-12
(-6 only)

-2.0
= (2.0 mm)
.0787"

GUIDANCE (EBTM-VT)	KEYING							
	-A	-B	-C	-D	-E	-F	-G	-H
-L/-R								

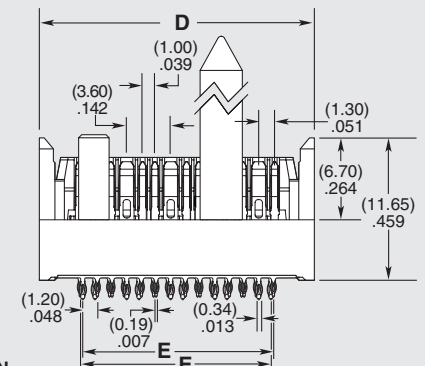
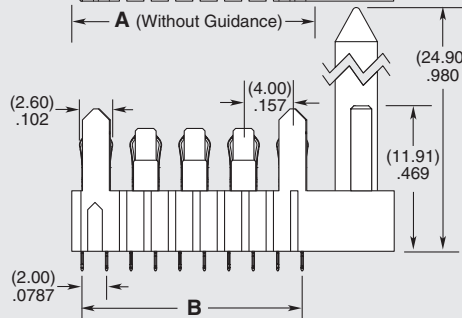
C (With Guidance)



A (Without Guidance)

NO. OF PAIRS PER COLUMN	D	E
-4	(22.50) .886	(15.60) .614
-6	(29.70) 1.169	(22.80) .898

COLUMNS	A	B	C
-06	(11.90) .469	(10.00) .394	(18.35) .722
-08	(15.90) .626	(14.00) .551	(22.35) .880
-10	(19.90) .783	(18.00) .709	(26.35) 1.037
-12	(23.90) .941	(22.00) .866	(30.35) 1.195



EBTM-4-10-2.0-S-VT-1-L-G SHOWN

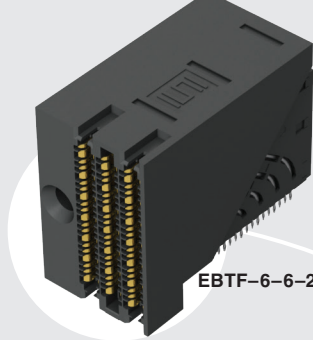
Notes:
Some lengths, styles and options are non-standard, non-returnable.

ExaMAX[®] is a registered trademark of AFCL.

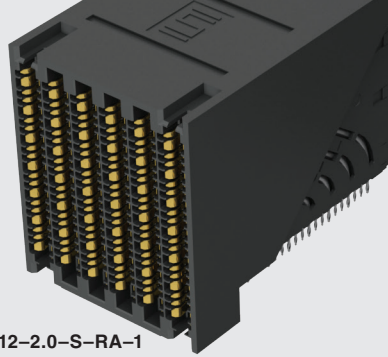
Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

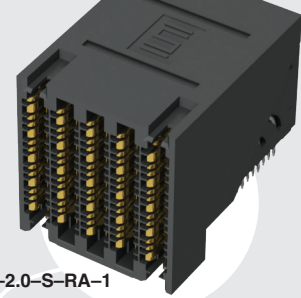
All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.



EBTF-6-6-2.0-S-RA-1-L

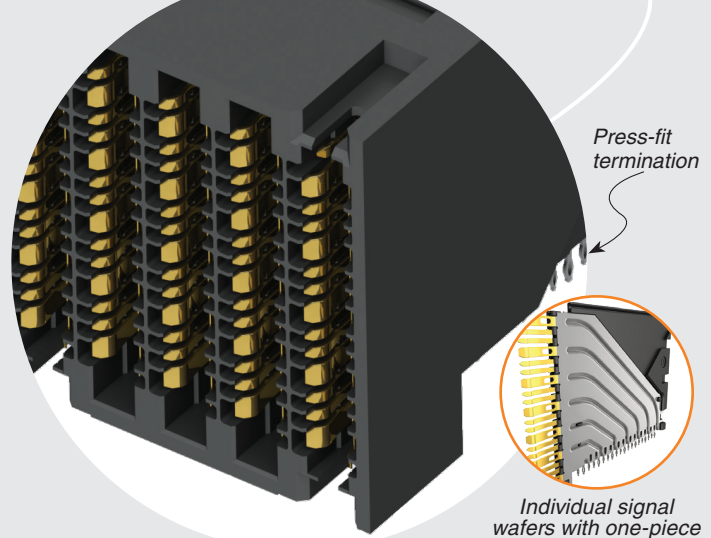
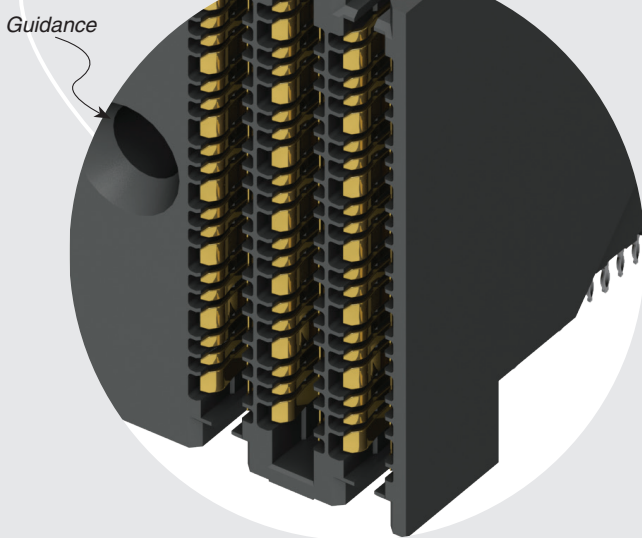


EBTF-6-12-2.0-S-RA-1



EBTF-4-10-2.0-S-RA-1

EBTM, EBTF-RA SERIES



PLATING

-S
= 30 μ" (0.76 μm)
Gold on contact area,
Matte Tin on tail

ORIENTATION

-VT
= Vertical
(EBTM only)

-RA
= Right-Angle
(EBTF-RA only)

1 GUIDANCE

(Leave Blank for no Guidance)

-L
= Left Guidance

-R
= Right Guidance

KEYING

(Only available with -L or -R guidance)
(Leave Blank for None)

-A thru -H
= Position of flat on Key
(See table for Key)

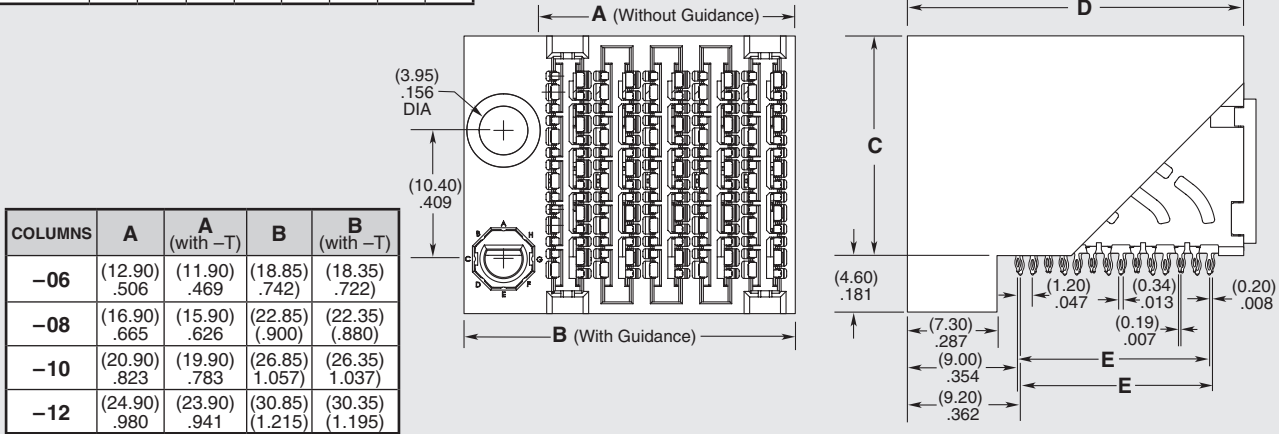
END WALLS

(Leave Blank for Thick End Wall)

-T
= Thin Walls
(EBTF-RA only)

GUIDANCE (EBTF-RA)	KEYING							
	-A	-B	-C	-D	-E	-F	-G	-H
-L/-R								

NO. OF PAIRS PER COLUMN	C	D	E
-4	(17.90) .705	(28.40) 1.118	(22.80) .898
-6	(25.10) .988	(35.60) 1.402	(22.80) .898



Due to technical progress, all designs, specifications and components are subject to change without notice.